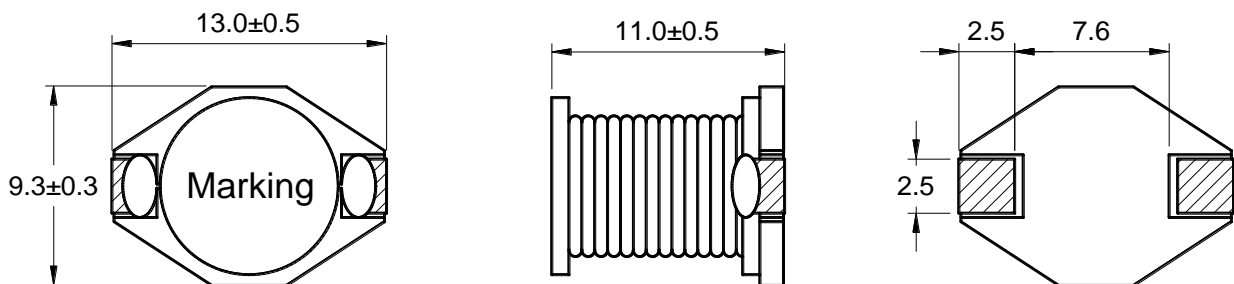




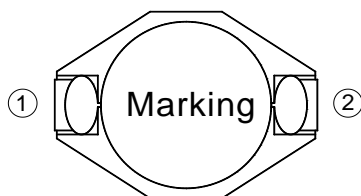
Outline: 产品概要

- Small size, high rated current, low DCR.
小尺寸，耐大电流，低直流电阻。
- Lead free product, RoHS compliant.
无铅产品，符合 RoHS 指令。
- Carrier tape packing, suitable for SMT process.
载带包装，适用于回流焊 SMT 工艺。
- Widely used in buck converter, displayer, laptop, automotive electronics, household appliance, and etc.
广泛应用于升降压转换器，显示器，笔记本电脑，汽车电子，家用电器等。
- Operating temperature : $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$
(Including coil's temperature rise)
工作温度： $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$ (包含线圈发热)

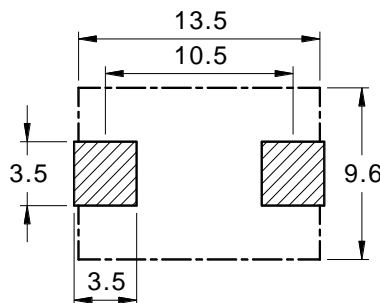
1 Appearance and dimensions (mm) 外形尺寸



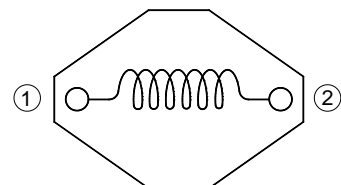
2 Marking 印字标识



3 Reference land pattern (mm) 参考基板尺寸



4 Schematic 原理图



5 Electrical characteristics

电气特性

Part No. 型号	Inductance (μH) 电感值 ※1 ±20%	D.C.R. (mΩ) 直流电阻		Saturation current (A) 饱和电流 ※2		Temperature rise current (A) 温升电流 ※3
		Typical	Max	Typical	Max	Typical
SPF3340-100M	10.0	21.5	25.8	10.5	8.40	4.54
SPF3340-120M	12.0	23.3	28.0	10.0	8.00	4.36
SPF3340-150M	15.0	30.4	36.5	9.50	7.60	3.82
SPF3340-180M	18.0	34.0	40.8	9.00	7.20	3.61
SPF3340-220M	22.0	44.0	52.8	8.40	6.72	3.17
SPF3340-270M	27.0	50.0	60.0	7.50	6.00	2.98
SPF3340-330M	33.0	56.0	67.2	6.90	5.52	2.81
SPF3340-390M	39.0	62.0	74.4	6.30	5.04	2.67
SPF3340-470M	47.0	79.5	95.0	5.90	4.72	2.36
SPF3340-560M	56.0	89.0	107	5.35	4.28	2.23
SPF3340-680M	68.0	120	143	4.85	3.88	1.93
SPF3340-820M	82.0	137	164	4.35	3.48	1.80
SPF3340-101M	100	153	184	4.00	3.20	1.70
SPF3340-121M	120	208	250	3.60	2.88	1.46
SPF3340-151M	150	239	287	3.30	2.64	1.36
SPF3340-181M	180	307	368	3.00	2.40	1.20
SPF3340-221M	220	350	420	2.70	2.16	1.12
SPF3340-271M	270	398	478	2.40	1.92	1.05
SPF3340-331M	330	502	602	2.20	1.76	0.94
SPF3340-391M	390	650	780	2.00	1.60	0.83
SPF3340-471M	470	714	857	1.85	1.48	0.79
SPF3340-561M	560	804	965	1.70	1.36	0.74
SPF3340-681M	680	1,030	1,236	1.50	1.20	0.66
SPF3340-821M	820	1,310	1,572	1.40	1.12	0.58
SPF3340-102M	1,000	1,570	1,884	1.20	0.96	0.53
SPF3340-152M	1,500	2,350	2,820	1.00	0.80	0.43

■ All data is tested based on 25°C ambient temperature.

所有数据基于环境温度 25°C 条件下测试。

※1 Inductance measure condition at 1kHz, 0.25V.

电感测试条件为 1kHz, 0.25V。

※2 Saturation current: the actual value of DC current when the inductance decrease 20% of its initial value.

饱和电流: 电感值下降其初始值的 20% 时所加载的实际直流电流值。

※3 Temperature rise current: the actual value of DC current when the temperature rise is $\Delta T40^{\circ}\text{C}$ ($T_a=25^{\circ}\text{C}$).

温升电流: 使产品温度上升到 $\Delta T40^{\circ}\text{C}$ 时所加载的实际直流电流值 ($T_a=25^{\circ}\text{C}$)。

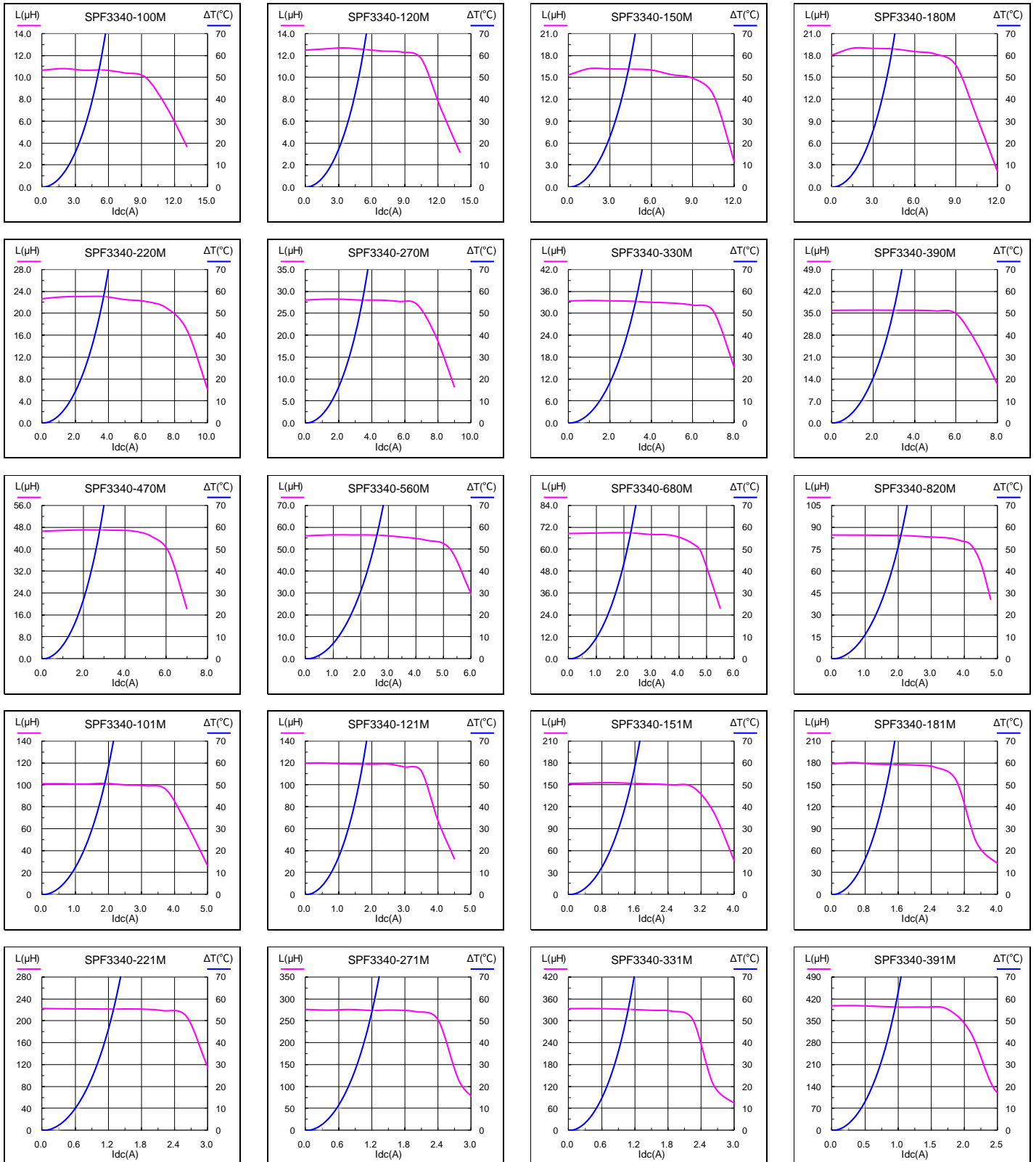
※ Special remind: Circuit design, component placement, PWB size and thickness, cooling system and etc.

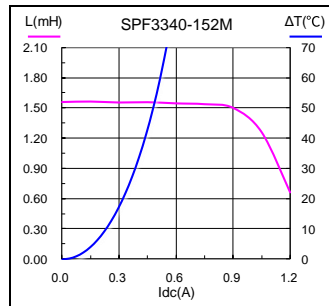
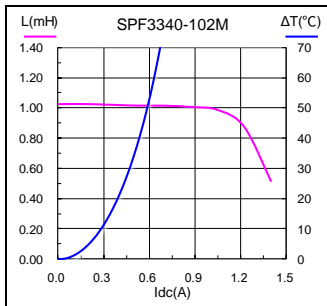
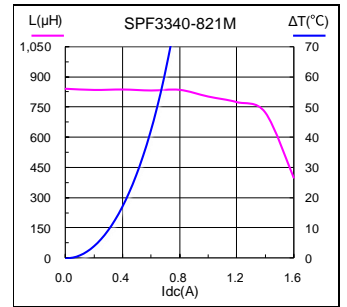
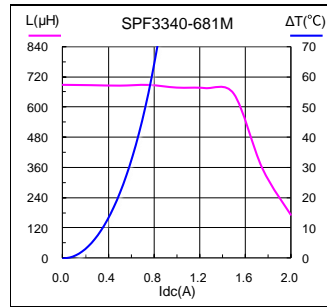
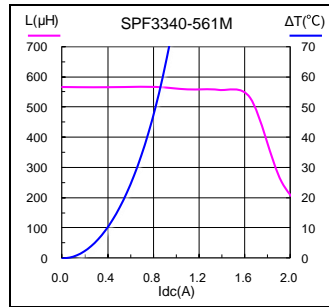
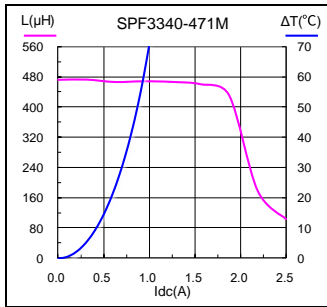
all will affect the product temperature. Please verify the product temperature in the final application.

特别提醒: 线路设计, 组件布局, 印刷线路板(PWB)尺寸及厚度, 散热系统等均会影响产品温度。

请务必在最终应用时, 验证产品发热状况。

6 Saturation current VS temperature rise current curve 饱和电流 VS 温升电流曲线



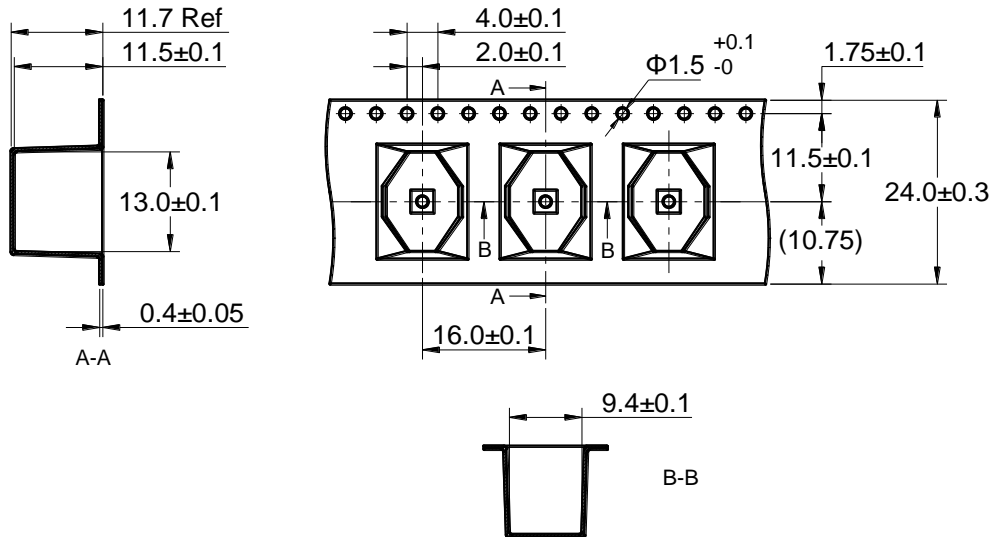


7 Packing specification

包装规格

7.1 Carrier tape dimensions (mm)

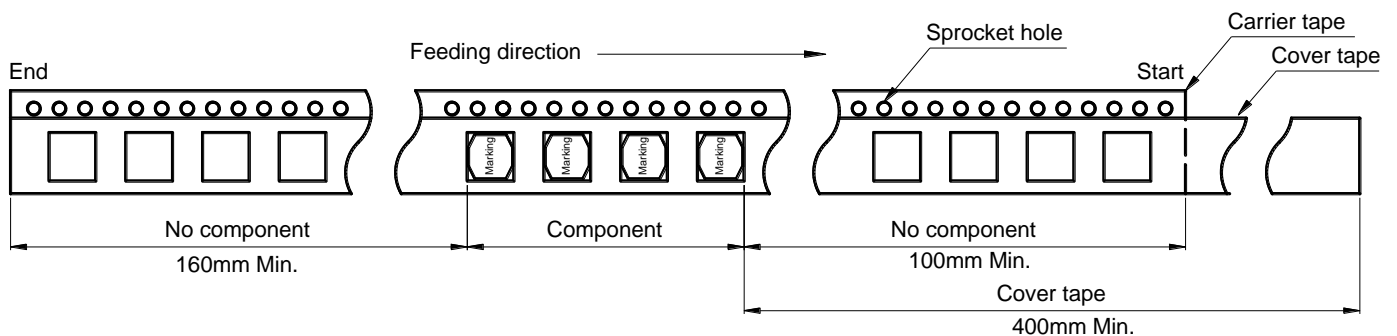
载带尺寸



※ Packing is referred to the international standard IEC 60286-3.
包装参照国际标准 IEC 60286-3。

7.2 Tape direction

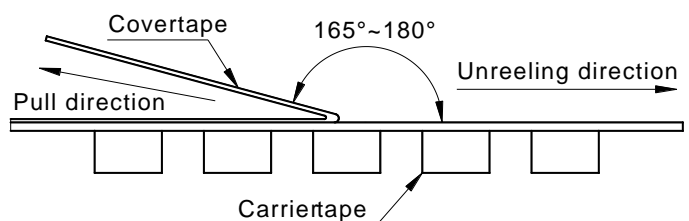
捆包方向



7.3 Cover tape peel off condition

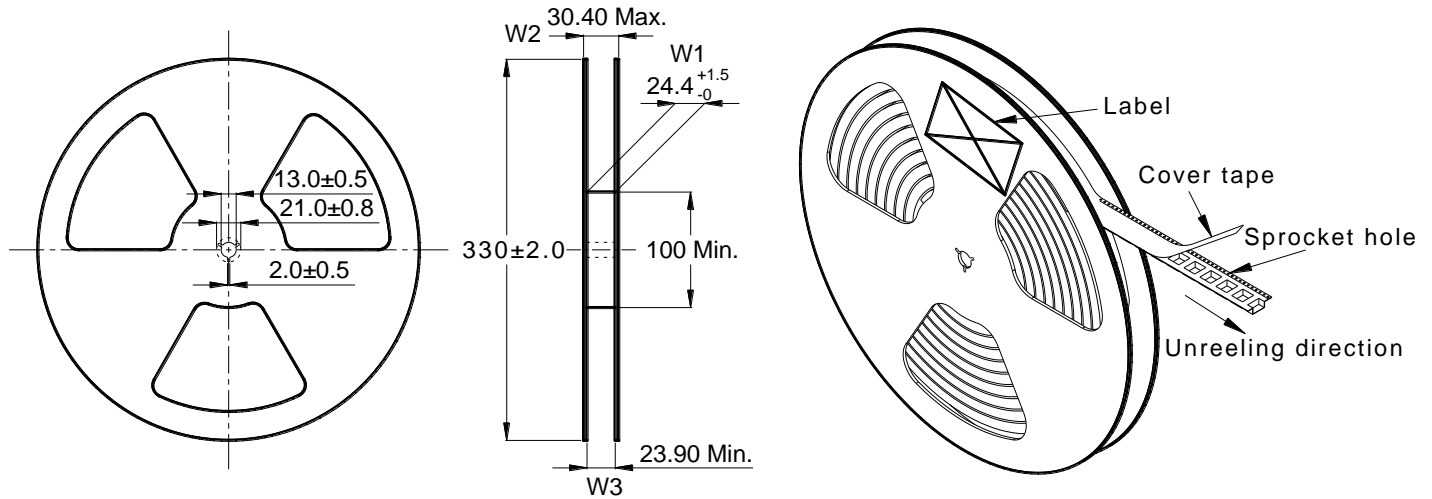
盖带剥离条件

- Cover tape peel force shall be 0.1 to 1.3N.
盖带剥离力度为 0.1~1.3N。
- Reference peel speed 300±10mm/min.
参考剥离速度 300±10mm/分钟。



7.4 Reel dimensions (mm)

卷盘尺寸



7.5 Carton dimensions and packing quantity

包装箱尺寸和包装数量

■ Inner Carton: 365×345×105mm
内包装盒

■ Out Carton : 385×365×245mm
外包装箱

Product Series 产品系列	Quantity / Reel 数量 / 卷	Inner Carton Quantity 内盒 包装数量	Out Carton Quantity 外箱 包装总数量
SPF3340	350pcs	(350×3) = 1050pcs	(1050×2) = 2100pcs

7.6 Label making

标签标识

The following items will be marked on the reel of product label and shipping label.
以下项目将明确标识于产品卷盘标签以及运输标签上。

Production Label 产品标签
■ Part No. 产品型号
■ Electrical Information 产品电性信息
■ Quantity 数量
■ Packing No. 包装流水号

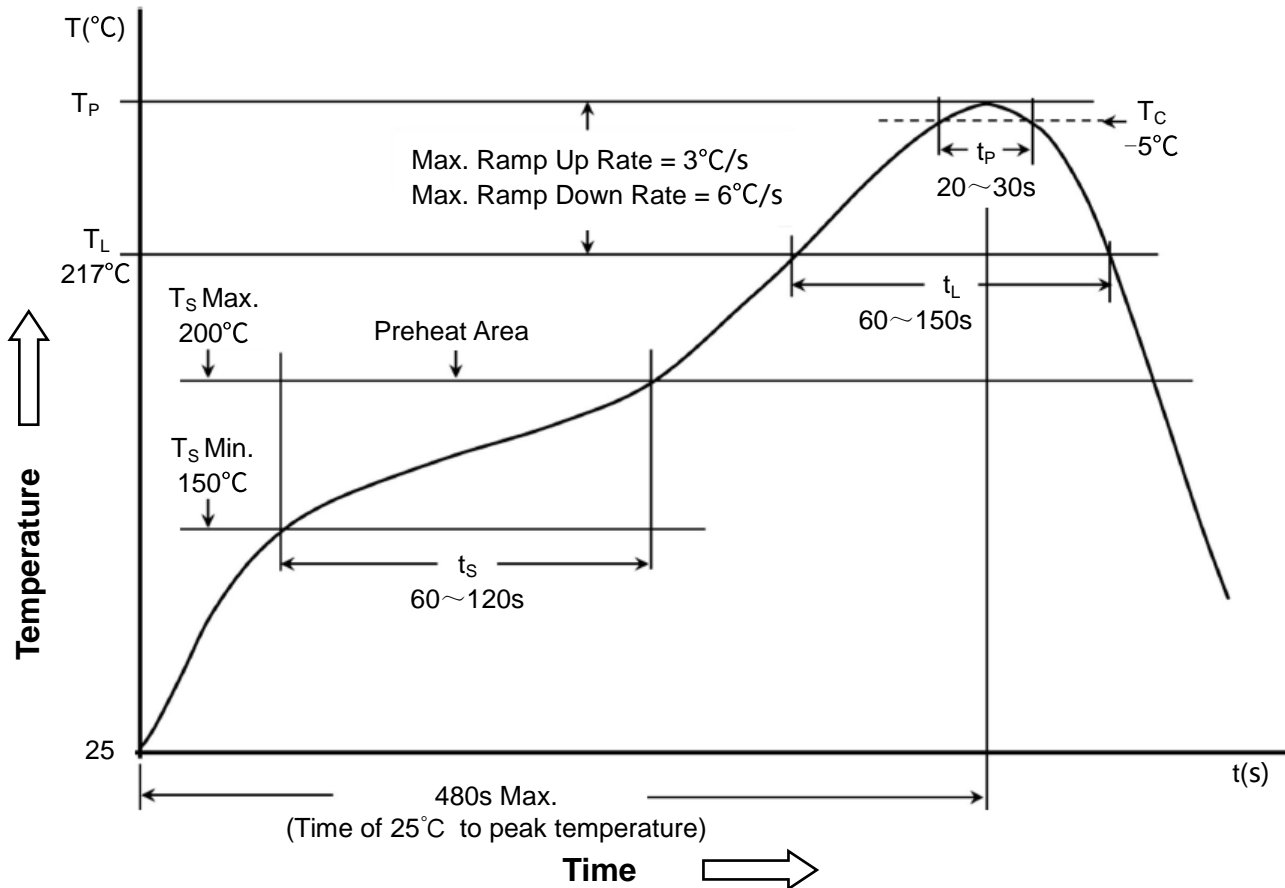
Shipping Label 运输标签
■ Customer Name 客户名称
■ Customer Part No. 客户型号
■ Supplier Part No. 供应商型号
■ Supplier Name 供应商名称
■ Country of origin 产品产地

8 Soldering specification

焊接规格

8.1 Reflow profile for SMT components

SMT 回流焊温度曲线



8.2 Classification of peak package body temperature (T_P)

封装体峰值温度(T_P)分类

	Package Thickness 封装厚度	Package Volume 封装体积		
		<350 mm ³	350~2000 mm ³	>2000 mm ³
PB-Free Assembly 无铅装配	<1.6mm	260°C	260°C	260°C
	1.6~2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

※ Reflow is referred to standard IPC/JEDEC J-STD-020D.
回流焊参照标准 IPC/JEDEC J-STD-020D.